IXYS
INTEGRATED CIRCUITS DIVISION

PLA150
Single-Pole, Normally Open OptoMOS® Relay

Parameters	Ratings	Units
Blocking Voltage	250	V_P
Load Current	250	mA_{rms} / mA_{DC}
On-Resistance (max)	7	Ω

Features
- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Small 6-Pin Package
- Flammability Rating UL 94 V-0

Applications
- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebooks, Pocket Size)
  - Hook Switch
  - Dial Pulsing
  - Ground Start
  - Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description
PLA150 is a 250V, 250mA, 7Ω, single-pole, normally open (1-Form-A) solid state relay that uses optically coupled MOSFET technology to provide 3750V_{rms} input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

This performance leader features high peak load current handling capability with a very low on-resistance.

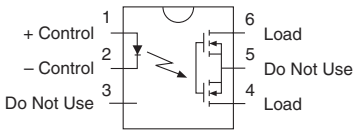
Approvals
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component: Certificate available on our website

Ordering Information

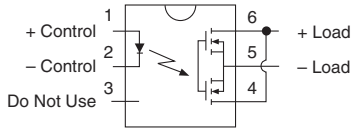
Part #	Description
PLA150	6-Pin DIP (50/Tube)
PLA150S	6-Pin Surface Mount (50/Tube)
PLA150STR	6-Pin Surface Mount (1000/Reel)

Pin Configuration

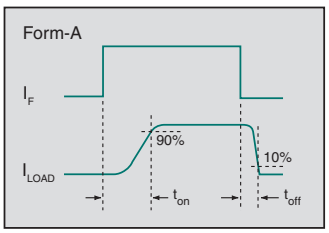
AC/DC Configuration



DC Only Configuration



Switching Characteristics of Normally Open Devices



Pb RoHS e3

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Absolute Maximum Ratings @ 25ºC

Parameter	Ratings	Units
Peak Blocking Voltage	250	V_P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	150	mW
Total Package Dissipation [2]	800	mW
Isolation Voltage, Input to Output	3750	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33 mW / °C
[2] Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25ºC

Parameters	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current, Continuous						
AC/DC Configuration	-	I_L	-	-	250	mA_{rms} / mA_{DC}
DC Configuration	-	I_L	-	-	350	mA_{DC}
Peak Load Current	10ms	I_{LPK}	-	-	±500	mA_P
On-Resistance [1]						
AC/DC Configuration	I_L=250mA	R_{ON}	-	-	7	Ω
DC Configuration	I_L=350mA	R_{ON}	-	2	3	Ω
Off-State Leakage Current	V_L=250V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=5mA, V_L=10V	t_{on}	-	-	2.5	ms
Turn-Off	I_F=5mA, V_L=10V	t_{off}	-	-	0.5	ms
Output Capacitance	I_F=0mA, V_L=50V, f=1MHz	C_{OUT}	-	110	-	pF
Input Characteristics						
Input Control Current to Activate	I_L=250mA	I_F	-	-	5	mA
Input Control Current to Deactivate	-	I_F	0.4	0.7	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.2	1.5	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Common Characteristics						
Input to Output Capacitance	V_{IO}=0V, f=1MHz	C_{IO}	-	3	-	pF

[1] Measurement taken within 1 second of on-time.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
PLA150 / PLA150S	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

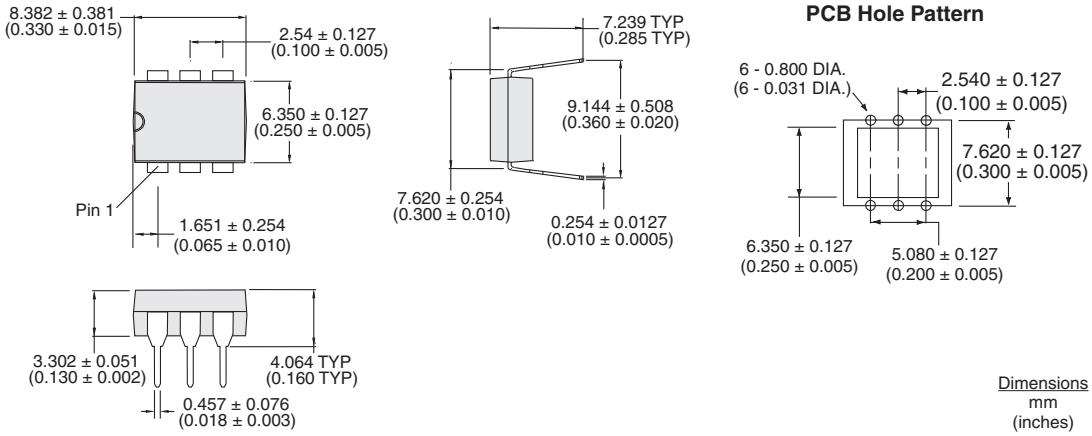
Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
PLA150	250°C	30 seconds	1
PLA150S	250°C	30 seconds	3

Board Wash

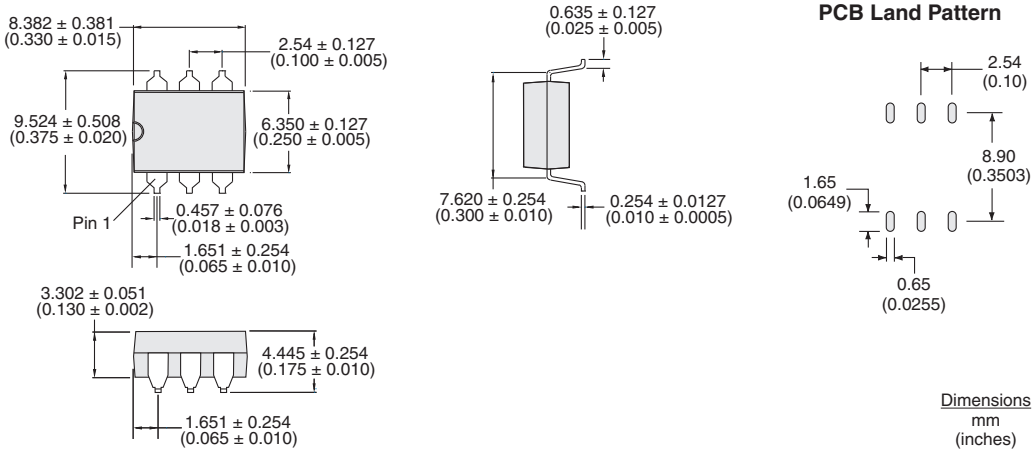
IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

Mechanical Dimensions

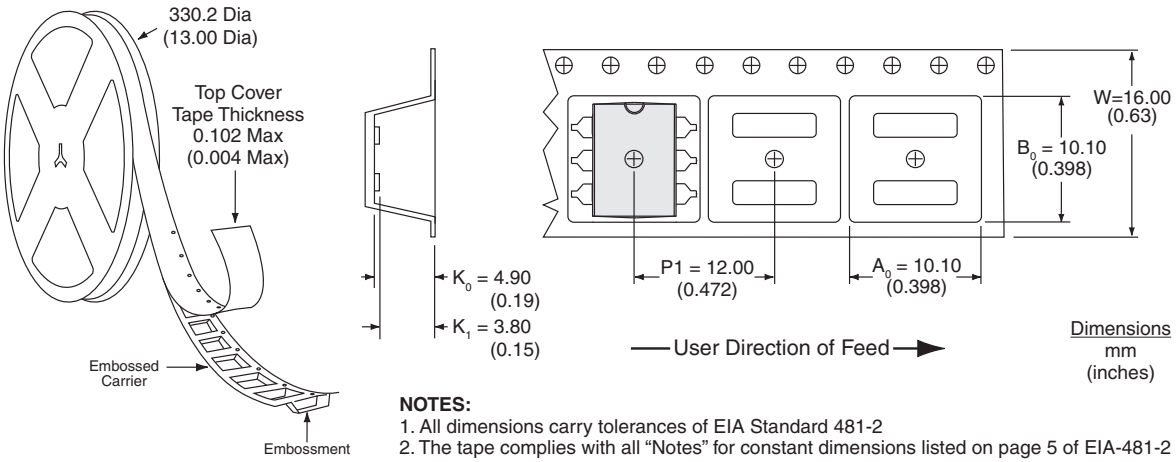
PLA150



PLA150S



PLA150STR Tape & Reel



NOTES:
1. All dimensions carry tolerances of EIA Standard 481-2
2. The tape complies with all “Notes” for constant dimensions listed on page 5 of EIA-481-2

For additional information please visit our website at: www.ixysic.com

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